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Applications of "<u>Embedded -</u> <u>Microcontrollers</u>"

Details

Product Status	Active
Core Processor	dsPIC
Core Size	16-Bit
Speed	40 MIPs
Connectivity	I ² C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	21
Program Memory Size	6КВ (2К х 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	256 x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 6x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	28-SSOP (0.209", 5.30mm Width)
Supplier Device Package	28-SSOP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33fj06gs102a-i-ss

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

TABLE 4-19: CONSTANT CURRENT SOURCE REGISTER MAP

F	ile Name	ADR	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
15	SRCCON	0500	ISRCEN	—		_	—	OUTSEL<2:0>		—	—			ISRCCA	AL<5:0>			0000	

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

TABLE 4-20: HIGH-SPEED 10-BIT ADC REGISTER MAP FOR dsPIC33FJ06GS001 AND dsPIC33FJ06GS101A

			1	1					1	1		1	1					1
SFR Name	SFR Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
ADCON	0300	ADON	_	ADSIDL	SLOWCLK	—	GSWTRG	_	FORM	EIE	ORDER	SEQSAMP	ASYNCSAMP	_	Α	DCS<2:0	>	0003
ADPCFG	0302	_	_	_	-	_	_	_	—	PCFG7	PCFG6	_	—	PCFG3	PCFG2	PCFG1	PCFG0	0000
ADSTAT	0306	_	_	_	_	_	_	—	—	_	P6RDY	_	—	P3RDY	_	P1RDY	P0RDY	0000
ADBASE	0308							A	DBASE<	15:1>							—	0000
ADCPC0	030A	IRQEN1	PEND1	SWTRG1		TRG	SRC1<4:0>			IRQEN0	PEND0	SWTRG0		TRGS	RC0<4:0>			0000
ADCPC1	030C	IRQEN3	PEND3	SWTRG3		TRG	SRC3<4:0>			_	_	_	—	_	_	_	_	0000
ADCPC3	0310	_	_	_	_	_	—	_	—	IRQEN6	PEND6	SWTRG6		TRGS	RC6<4:0>			0000
ADCBUF0	0320								ADC D	ata Buffer 0)							XXXX
ADCBUF1	0322								ADC D	ata Buffer 1								XXXX
ADCBUF2	0324								ADC D	ata Buffer 2								XXXX
ADCBUF3	0326								ADC D	ata Buffer 3	;							XXXX
ADCBUF6	032C								ADC D	ata Buffer 6	i		X					XXXX
ADCBUF7	032E								ADC D	ata Buffer 7	,		XX					XXXX
ADCBUF12	0338	ADC Data Buffer 12 xxx								XXXX								
ADCBUF13	033A		ADC Data Buffer 13 xxxx															

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

TABLE 4-28:PERIPHERAL PIN SELECT OUTPUT REGISTER MAP FOR dsPIC33FJ06GS102A, dsPIC33FJ06GS202A AND
dsPIC33FJ09GS302

File Name	Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
RPOR0	06D0	—	—			RP1	R<5:0>			—	—			RP0R	<5:0>			0000
RPOR1	06D2	_	_			RP3	3R<5:0>			_	_			RP2R	<5:0>			0000
RPOR2	06D4	_	_			RP5	5R<5:0>			_	_			RP4R	<5:0>			0000
RPOR3	06D6	_	_			RP7	′R<5:0>			_	_			RP6R	<5:0>			0000
RPOR4	06D8	_	_			RPS)R<5:0>			_	_			RP8R	<5:0>			0000
RPOR5	06DA	_	_			RP1	1R<5:0>			_	_			RP10R	<5:0>			0000
RPOR6	06DC	_	_			RP1	3R<5:0>			_	_			RP12R	<5:0>			0000
RPOR7	06DE	_	_			RP1	5R<5:0>			_	_	RP14R<5:0>				0000		
RPOR16	06F0	_	_			RPS	33<5:0>			_	_	RP32<5:0>				0000		
RPOR17	06F2	_	_			RPS	35<5:0>				_	RP34<5:0>					0000	

Legend: x = unknown value on Reset, - = unimplemented, read as '0'. Reset values are shown in hexadecimal.

4.7.3 READING DATA FROM PROGRAM MEMORY USING PROGRAM SPACE VISIBILITY

The upper 32 Kbytes of data space may optionally be mapped into any 16K word page of the program space. This option provides transparent access to stored constant data from the data space without the need to use special instructions (such as TBLRDL or TBLRDH).

Program space access through the data space occurs if the Most Significant bit of the data space EA is '1' and program space visibility is enabled by setting the PSV bit in the Core Control register (CORCON<2>). The location of the program memory space to be mapped into the data space is determined by the Program Space Visibility Page register (PSVPAG). This 8-bit register defines any one of 256 possible pages of 16K words in program space. In effect, PSVPAG functions as the upper 8 bits of the program memory address, with the 15 bits of the EA functioning as the lower bits. By incrementing the PC by 2 for each program memory word, the lower 15 bits of data space addresses directly map to the lower 15 bits in the corresponding program space addresses.

Data reads to this area add a cycle to the instruction being executed, since two program memory fetches are required. Although each data space address 0x8000 and higher maps directly into a corresponding program memory address (see Figure 4-10), only the lower 16 bits of the 24-bit program word are used to contain the data. The upper 8 bits of any program space location used as data should be programmed with '1111 1111' or '0000 0000' to force a NOP. This prevents possible issues should the area of code ever be accidentally executed.

Note: PSV access is temporarily disabled during table reads/writes.

For operations that use PSV and are executed outside a REPEAT loop, the MOV and MOV. D instructions require one instruction cycle in addition to the specified execution time. All other instructions require two instruction cycles in addition to the specified execution time.

For operations that use PSV, and are executed inside a REPEAT loop, these instances require two instruction cycles in addition to the specified execution time of the instruction:

- · Execution in the first iteration
- · Execution in the last iteration
- Execution prior to exiting the loop due to an interrupt
- Execution upon re-entering the loop after an interrupt is serviced

Any other iteration of the REPEAT loop will allow the instruction using PSV to access data, to execute in a single cycle.



FIGURE 4-10: PROGRAM SPACE VISIBILITY OPERATION

5.2 RTSP Operation

The dsPIC33FJ06GS001/101A/102A/202A and dsPIC33FJ09GS302 Flash program memory array is organized into rows of 64 instructions or 192 bytes. RTSP allows the user application to erase a page of memory, which consists of eight rows (512 instructions) at a time, and to program one row or one word at a time. Table 25-12 shows typical erase and programming times. The 8-row erase pages and single row write rows are edge-aligned from the beginning of program memory, on boundaries of 1536 bytes and 192 bytes, respectively.

The program memory implements holding buffers that can contain 64 instructions of programming data. Prior to the actual programming operation, the write data must be loaded into the buffers sequentially. The instruction words loaded must always be from a group of 64 boundary.

The basic sequence for RTSP programming is to set up a Table Pointer, then do a series of TBLWT instructions to load the buffers. Programming is performed by setting the control bits in the NVMCON register. A total of 64 TBLWTL and TBLWTH instructions are required to load the instructions.

All of the table write operations are single-word writes (two instruction cycles) because only the buffers are written. A programming cycle is required for programming each row.

5.3 Programming Operations

A complete programming sequence is necessary for programming or erasing the internal Flash in RTSP mode. The processor stalls (waits) until the programming operation is finished.

The programming time depends on the FRC accuracy (see Table 25-19) and the value of the FRC Oscillator Tuning register (see Register 8-4). Use the following formula to calculate the minimum and maximum values for the Row Write Time, Page Erase Time and Word Write Cycle Time parameters (see Table 25-12).

EQUATION 5-1: PROGRAMMING TIME



For example, if the device is operating at +125°C, the FRC accuracy will be $\pm 5\%$. If the TUN<5:0> bits (see Register 8-4) are set to `b111111, the minimum row write time is equal to Equation 5-2.

EQUATION 5-2: MINIMUM PAGE ERASE TIME

$$T_{RW} = \frac{168517 \ Cycles}{7.37 \ MHz \times (1 + 0.05) \times (1 - 0.00375)} = 21.85 ms$$

The maximum row write time is equal to Equation 5-3.

EQUATION 5-3: MAXIMUM PAGE ERASE TIME

$$T_{RW} = \frac{168517 \text{ Cycles}}{7.37 \text{ MHz} \times (1 - 0.05) \times (1 - 0.00375)} = 24.16 \text{ ms}$$

Setting the WR bit (NVMCON<15>) starts the operation, and the WR bit is automatically cleared when the operation is finished.

5.4 Control Registers

Two SFRs are used to read and write the program Flash memory: NVMCON and NVMKEY.

The NVMCON register (Register 5-1) controls which blocks are to be erased, which memory type is to be programmed and the start of the programming cycle.

NVMKEY is a write-only register that is used for write protection. To start a programming or erase sequence, the user application must consecutively write 0x55 and 0xAA to the NVMKEY register. Refer to **Section 5.3 "Programming Operations"** for further details.

REGISTER /-2	4: IPC5:	INTERRUPT	PRIORITY		EGISTERS					
U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0			
—	_	—	_		—	—	—			
bit 15							bit 8			
U-0	U-0	U-0	U-0	U-0	R/W-1	R/W-0	R/W-0			
—	_	_	_			INT1IP<2:0>				
bit 7							bit 0			
Legend:										
R = Readable bit W = Writable bit U = Unimplemented bit, read as '0'										
-n = Value at PC)R	'1' = Bit is set		'0' = Bit is cleared x = Bit is unknown						
•										

bit 15-3	Unimplemented: Read as '0)'
----------	---------------------------	----

bit 2-0 INT1IP<2:0>: External Interrupt 1 Priority bits 111 = Interrupt is Priority 7 (highest priority interrupt) ٠ 001 = Interrupt is Priority 1

000 = Interrupt source is disabled

REGISTER 7-25: IPC7: INTERRUPT PRIORITY CONTROL REGISTER 7

U-0	U-1	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8
U-0	R/W-1	R/W-0	R/W-0	U-0	U-0	U-0	U-0
—		INT2IP<2:0>		—	—	—	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read	l as '0'
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-7 Unimplemented: Read as '0' bit 6-4 INT2IP<2:0>: External Interrupt 2 Priority bits 111 = Interrupt is Priority 7 (highest priority interrupt) 001 = Interrupt is Priority 1 000 = Interrupt source is disabled bit 3-0 Unimplemented: Read as '0'

9.0 POWER-SAVING FEATURES

- Note 1: This data sheet summarizes the features of the dsPIC33FJ06GS001/101A/102A/ 202A and dsPIC33FJ09GS302 families of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to Section 9. "Watchdog Timer (WDT) and Power-Saving Modes" (DS70196) in the "dsPIC33F/ PIC24H Family Reference Manual", which is available from the Microchip web site (www.microchip.com).
 - Some registers and associated bits described in this section may not be available on all devices. Refer to Section 4.0 "Memory Organization" in this data sheet for device-specific register and bit information.

These devices provide the ability to manage power consumption by selectively managing clocking to the CPU and the peripherals. In general, a lower clock frequency and a reduction in the number of circuits being clocked constitutes lower consumed power. Devices can manage power consumption in four different ways:

- Clock Frequency
- Instruction-Based Sleep and Idle modes
- Software Controlled Doze mode
- Selective Peripheral Control in Software

Combinations of these methods can be used to selectively tailor an application's power consumption while still maintaining critical application features, such as timing-sensitive communications.

9.1 Clock Frequency and Clock Switching

These devices allow a wide range of clock frequencies to be selected under application control. If the system clock configuration is not locked, users can choose low-power or high-precision oscillators by simply changing the NOSC<2:0> bits (OSCCON<10:8>). The process of changing a system clock during operation, as well as limitations to the process, are discussed in more detail in **Section 8.0 "Oscillator Configuration"**.

9.2 Instruction-Based Power-Saving Modes

The devices have two special power-saving modes that are entered through the execution of a special PWRSAV instruction. Sleep mode stops clock operation and halts all code execution. Idle mode halts the CPU and code execution, but allows peripheral modules to continue operation. The assembler syntax of the PWRSAV instruction is shown in Example 9-1.

Note: SLEEP_MODE and IDLE_MODE are constants defined in the assembler include file for the selected device.

Sleep and Idle modes can be exited as a result of an enabled interrupt, WDT time-out or a device Reset. When the device exits these modes, it is said to wake-up.

9.2.1 SLEEP MODE

The following occur in Sleep mode:

- The system clock source is shut down. If an on-chip oscillator is used, it is turned off.
- The device current consumption is reduced to a minimum, provided that no I/O pin is sourcing current.
- The Fail-Safe Clock Monitor does not operate since the system clock source is disabled.
- The LPRC clock continues to run in Sleep mode if the WDT is enabled.
- The WDT, if enabled, is automatically cleared prior to entering Sleep mode.
- Some device features or peripherals may continue to operate. This includes items, such as the Input Change Notification (ICN) on the I/O ports or peripherals that use an external clock input.
- Any peripheral that requires the system clock source for its operation is disabled.

The device will wake-up from Sleep mode on any of these events:

- · Any interrupt source that is individually enabled
- Any form of device Reset
- A WDT time-out

On wake-up from Sleep mode, the processor restarts with the same clock source that was active when Sleep mode was entered.

EXAMPLE 9-1: PWRSAV INSTRUCTION SYNTAX

PWRSAV#SLEEP_MODE; Put the device into SLEEP modePWRSAV#IDLE_MODE; Put the device into IDLE mode

10.7 I/O Helpful Tips

- In some cases, certain pins, as defined in 1. Table 25-9 under "Injection Current", have internal protection diodes to VDD and VSS. The term, "Injection Current", is also referred to as "Clamp Current". On designated pins, with sufficient external current limiting precautions by the user, I/O pin input voltages are allowed to be greater or less than the data sheet absolute maximum ratings with respect to the VSS and VDD supplies. Note that when the user application forward biases either of the high or low side internal input clamp diodes, that the resulting current being injected into the device that is clamped internally by the VDD and VSS power rails, may affect the ADC accuracy by four to six counts.
- I/O pins that are shared with any analog input pin 2. (i.e., ANx) are always analog pins by default after any Reset. Consequently, any pin(s) configured as an analog input pin, automatically disables the digital input pin buffer. As such, any attempt to read a digital input pin will always return a '0', regardless of the digital logic level on the pin if the analog pin is configured. To use a pin as a digital I/O pin on a shared ANx pin, the user application needs to configure the Analog Pin register in the ADC module (i.e., ADPCFG) by setting the appropriate bit that corresponds to that I/O port pin to a '1'. On devices with more than one ADC, both analog pin configurations for both ADC modules must be configured as a digital I/O pin for that pin to function as a digital I/O pin.
- **Note:** Although it is not possible to use a digital input pin when its analog function is enabled, it is possible to use the digital I/O output function, TRISx = 0×0 , while the analog function is also enabled. However, this is not recommended, particularly if the analog input is connected to an external analog voltage source, which would create signal contention between the analog signal and the output pin driver.
- 3. Most I/O pins have multiple functions. Referring to the device pin diagrams in the data sheet, the priorities of the functions allocated to any pins are indicated by reading the pin name from left-to-right. The left most function name takes precedence over any function to its right in the naming convention; for example: AN2/CMP1C/CMP2A/RA2. This indicates that AN2 is the highest priority in this example and will supersede all other functions to its right in the list. Those other functions to its right, even if enabled, would not work as long as any other function to its left was enabled. This rule applies to all of the functions listed for a given pin.

- 4. Each CN pin has a configurable internal weak pull-up resistor. The pull-ups act as a current source connected to the pin and eliminates the need for external resistors in certain applications. The internal pull-up is to ~(VDD – 0.8), not VDD. This is still above the minimum VIH of CMOS and TTL devices.
- 5. When driving LEDs directly, the I/O pin can source or sink more current than what is specified in the VOH/IOH and VOL/IOL DC Characteristics specification. The respective IOH and IOL current rating only applies to maintaining the corresponding output at or above the VOH, and at or below the VOL levels. However, for LEDs, unlike digital inputs of an externally connected device, they are not governed by the same minimum VIH/VIL levels. An I/O pin output can safely sink or source any current less than that listed in the "Absolute Maximum Ratings(1)" in Section 25.0, Electrical Characteristics of this data sheet. For example:

VOH = 2.4V @ IOL = -6 mA and VDD = 3.3V

The maximum output current sourced by any 4x I/O pin = 15 mA.

LED source current <15 mA is technically permitted. Refer to the VOH/IOH graphs in Section 26.0 "DC and AC Device Characteristics Graphs" for additional information.

10.8 I/O Resources

Many useful resources related to I/O are provided on the Microchip web site (www.microchip.com).

10.8.1 KEY RESOURCES

- "dsPIC33F/PIC24H Family Reference Manual", Section 10. "I/O Ports" (DS70193)
- Code Samples
- Application Notes
- Software Libraries
- Webinars
- All related "*dsPIC33F/PIC24H Family Reference Manual*" Sections
- Development Tools

REGISTER	10-12: RPIN	R31: PERIPHI	ERAL PIN S	SELECT INPU	T REGISTE	R 31	
U-0	U-0	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1
_	—			FLT5	R<5:0>		
bit 15							bit 8
U-0	U-0	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1
—	—			FLT4	R<5:0>		
bit 7							bit (
Legend:							
R = Readab	le bit	W = Writable	bit	U = Unimpler	mented bit, rea	ad as '0'	
-n = Value a	t POR	'1' = Bit is set		'0' = Bit is cle	ared	x = Bit is unk	nown
bit 15-14	Unimpleme	nted: Read as '	0'				
bit 13-8	FLT5R<5:0>	: Assign PWM I	ault Input 5	(FLT5) to the C	orresponding	RPn Pin bits	
	111111 = In	put tied to Vss					
	100011 = In	put tied to RP35	5				
	100010 = In	put tied to RP34	ł				
	100001 = In	put tied to RP33	3				
	100000 = In	put tied to RP32	2				
	•						
	•						
	•						
	00000 = Inp	ut fied to RP0					
bit 7-6	Unimpleme	nted: Read as	0'				
bit 5-0	FLT4R<5:0>	: Assign PWM I	ault Input 4	(FLT4) to the C	orresponding	RPn Pin bits	
	111111 = In	put tied to Vss					
	100011 = In	put tied to RP35	5				
	100010 = In	put tied to RP34	ł				
	100001 = In	put tied to RP33	3				
	100000 = In	put tied to RP32	2				
	•						
	•						
	•						
	00000 = Inp	ut tied to RP0					

REGISTER 15-6: PWMCONx: PWMx CONTROL REGISTER (CONTINUED)

3)
2

- 1 = Center-Aligned mode is enabled
- 0 = Center-Aligned mode is disabled

bit 1 XPRES: External PWM Reset Control bit⁽⁴⁾

1 = Current-limit source resets time base for this PWM generator if it is in Independent Time Base mode 0 = External pins do not affect PWM time base

- bit 0 IUE: Immediate Update Enable bit
 - 1 = Updates to the active MDC/PDCx/SDCx registers are immediate
 - 0 = Updates to the active MDC/PDCx/SDCx registers are synchronized to the PWM time base
- **Note 1:** Software must clear the interrupt status here and the corresponding IFSx bit in the interrupt controller.
 - 2: The Independent Time Base mode (ITB = 1) must be enabled to use Center-Aligned mode. If ITB = 0, the CAM bit is ignored.
 - **3:** These bits should be changed only when PTEN = 0. Changing the clock selection during operation will yield unpredictable results.
 - 4: To operate in External Period Reset mode, configure the CLMOD (FCLCONx<8>) bit = 0 and ITB (PWMCONx<9>) bit = 1.

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
			SPHASE	x<15:8> ^(1,2)			
bit 15							bit 8
R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
			SPHASE	Ex<7:0> ^(1,2)			
bit 7							bit 0
Legend:							
R = Readable	bit	W = Writable b	it	U = Unimpler	mented bit, rea	id as '0'	
-n = Value at F	POR	'1' = Bit is set		'0' = Bit is cle	ared	x = Bit is unkr	nown

bit 15-0 **SPHASEx<15:0>:** Secondary Phase Offset for PWMxL Output Pin bits^(1,2) (used in Independent PWM mode only)

- **Note 1:** If the ITB (PWMCONx<9>) bit = 0, the following applies based on the mode of operation:
 - Complementary, Redundant and Push-Pull Output mode (PMOD<1:0> (IOCONx<11:10>) = 00, 01 or 10), SPHASEx<15:0> = Not used.
 - True Independent Output mode PMOD<1:0> (IOCONx<11:10>) = 11), PHASEx<15:0> = Phase shift value for PWMxL only.
 - **2:** If the ITB (PWMCONx<9>) bit = 1, the following applies based on the mode of operation:
 - Complementary, Redundant and Push-Pull Output mode (PMOD<1:0> (IOCONx<11:10>) = 00, 01 or 10), SPHASEx<15:0> = Not used.
 - True Independent Output mode PMOD<1:0> (IOCONx<11:10>) = 11), PHASEx<15:0> = Independent time base period value for PWMxL only.

R/W-0	R/W-0	R/W-0	R/W-0	U-0	U-0	U-0	U-0
	TRGDI	V<3:0>		_	_	_	_
bit 15							bit 8
R/W-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
DTM ⁽¹⁾	_			TRGS	TRT<5:0>		
bit 7	•						bit 0
Legend:							
R = Readat	ble bit	W = Writable	bit	U = Unimplei	mented bit, rea	ad as '0'	
-n = Value a	at POR	'1' = Bit is set		'0' = Bit is cle	eared	x = Bit is unkr	nown
bit 15-12	TRGDIV<3:0 1111 = Trigg 1110 = Trigg 1101 = Trigg 1000 = Trigg 1011 = Trigg 1010 = Trigg 1000 = Trigg 0111 = Trigg 0101 = Trigg 0101 = Trigg 0101 = Trigg 0010 = Trigg 0011 = Trigg 0011 = Trigg 0011 = Trigg 0010 = Trigg 0001 = Trigg 0001 = Trigg 0001 = Trigg	D>: Trigger # Out ger output for ev ger output for ev	tput Divider I ery 16th trigg ery 15th trigg ery 14th trigg ery 13th trigg ery 12th trigg ery 11th trigg ery 9th trigge ery 8th trigge ery 6th trigge ery 5th trigge ery 3rd trigge ery 2nd trigge ery trigger ev	bits ger event ger event ger event ger event ger event ger event ger event er event ver event			
bit 11-8	Unimpleme	nted: Read as '	0'				
bit 7	DTM: Dual T	rigger Mode bit	(1)				
	1 = Seconda 0 = Seconda two sepa	ary trigger event ary trigger event arate PWM trigg	t is combinec is not combi jers are gene	l with the prima ned with the prine rated	ry trigger even mary trigger ev	t to create the P ent to create the	WM trigger. e PWM trigger;
bit 6	Unimpleme	nted: Read as '	0'				
bit 5-0	TRGSTRT<	5:0>: Trigger Po	stscaler Star	t Enable Select	bits		
	111111 = W	/ait 63 PWM cyc	les before ge	enerating the fir	st trigger even	t after the modu	le is enabled
	•						
	•						
	• 000010 = W 000001 = W 000000 = W	/ait 2 PWM cycle /ait 1 PWM cycle /ait 0 PWM cycle	es before ger e before gene e before gene	nerating the first erating the first erating the first	t trigger event a trigger event a trigger event a	after the module fter the module fter the module	e is enabled is enabled is enabled
N	T I		(D)				

REGISTER 15-13: TRGCONX: PWMx TRIGGER CONTROL REGISTER

Note 1: The secondary generator cannot generate PWM trigger interrupts.

16.0 SERIAL PERIPHERAL INTERFACE (SPI)

- Note 1: This data sheet summarizes the features of the dsPIC33FJ06GS001/101A/102A/ 202A and dsPIC33FJ09GS302 family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to Section 18. "Serial Peripheral Interface (SPI)" (DS70206) of the "dsPIC33F/ PIC24H Family Reference Manual", which is available from the Microchip web site (www.microchip.com).
 - 2: Some registers and associated bits described in this section may not be available on all devices. Refer to Section 4.0 "Memory Organization" in this data sheet for device-specific register and bit information.

The Serial Peripheral Interface (SPI) module is a synchronous serial interface useful for communicating with other peripheral or microcontroller devices. These peripheral devices can be serial EEPROMs, shift registers, display drivers, Analog-to-Digital Converters, etc. The SPI module is compatible with Motorola[®] SPI and SIOP.

Each SPI module consists of a 16-bit shift register, SPIxSR (where x = 1 or 2), used for shifting data in and out, and a buffer register, SPIxBUF. A control register, SPIxCON, configures the module. Additionally, a status register, SPIxSTAT, indicates status conditions.

The serial interface consists of 4 pins:

- · SDIx (serial data input)
- · SDOx (serial data output)
- · SCKx (shift clock input or output)
- SSx (active-low slave select)

In Master mode operation, SCKx is a clock output; in Slave mode, it is a clock input.



FIGURE 16-1: SPI MODULE BLOCK DIAGRAM

NOTES:

FIGURE 19-1: ADC BLOCK DIAGRAM FOR THE dsPIC33FJ06GS001 DEVICE



REGISTER 19-6: ADCPC1: ADC CONVERT PAIR CONTROL REGISTER 1

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
IRQEN3	⁽¹⁾ PEND3 ⁽¹⁾	SWTRG3 ⁽¹⁾			TRGSRC3<4:0>	(1)	
bit 15							bit 8
R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
IRQEN2	⁽²⁾ PEND2 ⁽²⁾	SWTRG2 ⁽²⁾			TRGSRC2<4:0>	(2)	
bit 7							bit 0
Logond:							
R = Reada	ble bit	W = Writable I	oit	U = Unimpl	emented bit. read	as '0'	
-n = Value	at POR	'1' = Bit is set		'0' = Bit is c	leared	x = Bit is unk	nown
bit 15	IROEN3: Inte	errunt Request F	=nable 3 hit(1)			
bit 15	1 = Enables	IRQ generation	when reques	ted conversion	on of channels AN	7 and AN6 is	completed
	0 = IRQ is no	ot generated	•				·
bit 14	PEND3: Pen	ding Conversion	h Status 3 bit	(1) S is pending:	aat whan aplacted	trigger is eas	orted
	0 = Conversi	on is complete		s is penuing;	SET WHEN SEIECTED	uigger is ass	
bit 13	SWTRG3: So	oftware Trigger	3 bit ⁽¹⁾				
	1 = Starts con	nversion of AN7	and AN6 (if	selected by t	he TRGSRCx bits)	(3)	
	0 = Conversi	omatically clear	ed by nardw ed	are when the	PEND3 bit is set.		
bit 12-8	TRGSRC3<4	I:0>: Trigger 3 S	Source Select	tion bits ⁽¹⁾			
	Selects trigge	er source for con	nversion of a	nalog channe	Is AN7 and AN6.		
	• •	erz penod mato	:r)				
	•						
	11011 = Res	served					
	11010 = PW	M Generator 4	current-limit A	ADC trigger			
	11000 = PW	M Generator 2	current-limit A	ADC trigger			
	10111 = PW	M Generator 1 (current-limit A	ADC trigger			
	•	serveu					
	•						
	10010 = Res	served					
	10001 = PW	M Generator 4	secondary tri	gger is select	ed		
	01111 = PW	M Generator 2	secondary tri	gger is select	ed		
	01110 = PW	M Generator 1	secondary tri	gger is select	ed		
	01100 = Tim	er1 period mate	h				
	•						
	•						
	01000 = Res	served	orimon, triago	or is solocted			
	00110 = Res	served	undiy ungge				
	00101 = PW	M Generator 2	orimary trigge	er is selected			
	00011 = PW	M Special Even	t Trigger is se	elected			
	00010 = Glo	bal software trig	ger is selecte	ed			
	00000 = No	conversion is er	nabled	20100			
Note 1: 2:	This bit is availabl This bit is availabl	e in dsPIC33FJ e in dsPIC33FJ	06GS001/10 ⁻ 06GS102A/2	1A and dsPIC 01A and dsP	C33FJ09GS302 de IC33FJ09GS302 d	vices only. levices only.	

3: The trigger source must be set as a global software trigger prior to setting this bit to '1'. If other conversions are in progress, conversion will be performed when the conversion resources are available.

		Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)						
			Operating	temperature	$-40^{\circ}C \le TA \le +$	85°C for Industrial		
				$-40^{\circ}C \le IA \le +125^{\circ}C$ for Extended				
Param.	Typical ⁽¹⁾	Max.	Units			Conditions		
Operating (Current (IDD) ⁽²⁾						
DC20d	15	23	mA	-40°C				
DC20a	15	23	mA	+25°C	3 3//	10 MIRS		
DC20b	15	23	mA	+85°C	5.5V	10 MIF 3		
DC20c	15	23	mA	+125°C				
DC21d	23	34	mA	-40°C				
DC21a	23	34	mA	+25°C	2 2)/	16 MIDS(3)		
DC21b	23	34	mA	+85°C	3.3V			
DC21c	23	34	mA	+125°C				
DC22d	25	38	mA	-40°C				
DC22a	25	38	mA	+25°C	2 2)/	20 MIDS(3)		
DC22b	25	38	mA	+85°C	3.3V	20 MIFS 7		
DC22c	25	38	mA	+125°C				
DC23d	34	51	mA	-40°C				
DC23a	34	51	mA	+25°C	2 2)/	20 MIDS(3)		
DC23b	34	51	mA	+85°C	3.3V	50 MIFS(*)		
DC23c	34	51	mA	+125°C				
DC24d	43	64	mA	-40°C				
DC24a	43	64	mA	+25°C	2.21/	40 MIDS(3)		
DC24b	43	64	mA	+85°C	- 3.3V	40 MIPS(*)		
DC24c	43	64	mA	+125°C				
DC25d	83	125	mA	-40°C		40 MIPS		
DC25a	83	125	mA	+25°C	3 3/1	See Note 2, except PWM and ADC		
DC25b	83	125	mA	+85°C	3.3V	are operating at maximum speed		
DC25c	83	125	mA	+125°C		(PTCON2 = 0x0000)		

TABLE 25-5: DC CHARACTERISTICS: OPERATING CURRENT (IDD)

Note 1: Data in "Typical" column is at 3.3V, +25°C unless otherwise stated.

2: IDD is primarily a function of the operating voltage and frequency. Other factors, such as I/O pin loading and switching rate, oscillator type, internal code execution pattern and temperature, also have an impact on the current consumption. The test conditions for all IDD measurements are as follows:

- Oscillator is configured in EC mode, OSC1 is driven with external square wave from rail-to-rail
- CLKO is configured as an I/O input pin in the Configuration Word
- All I/O pins are configured as inputs and pulled to Vss
- MCLR = VDD; WDT and FSCM are disabled
- CPU, SRAM, program memory and data memory are operational
- No peripheral modules are operating; however, every peripheral is being clocked (PMDx bits are all zeroed)
- CPU is executing while (1) statement
- **3:** These parameters are characterized but not tested in manufacturing.

FIGURE 25-6: INPUT CAPTURE (CAP1) TIMING CHARACTERISTICS



TABLE 25-25: INPUT CAPTURE TIMING REQUIREMENTS

АС СНА	RACTERI	STICS		$\begin{array}{l} \mbox{Standard Operating Conditions: 3.0V to 3.6V} \\ \mbox{(unless otherwise stated)} \\ \mbox{Operating temperature } -40^{\circ}C \leq TA \leq +85^{\circ}C \mbox{ for Industrial} \\ -40^{\circ}C \leq TA \leq +125^{\circ}C \mbox{ for Extended} \end{array}$				
Param.	Symbol	Characte	ristic ⁽¹⁾	Min.	Max.	Units	Conditions	
IC10	TccL	IC1 Input Low Time	No prescaler	0.5 Tcy + 20		ns		
			With prescaler	10	—	ns		
IC11	TccH	IC1 Input High Time	No prescaler	0.5 Tcy + 20	—	ns		
			With prescaler	10	—	ns		
IC15	TccP	IC1 Input Period		(Tcy + 40)/N		ns	N = prescale value (1, 4, 16)	

Note 1: These parameters are characterized but not tested in manufacturing.

FIGURE 25-7: OUTPUT COMPARE MODULE (OC1) TIMING CHARACTERISTICS



TABLE 25-26: OUTPUT COMPARE MODULE TIMING REQUIREMENTS

AC CHARACTERISTICS			$\begin{tabular}{lllllllllllllllllllllllllllllllllll$				
Param.	Symbol	Characteristic ⁽¹⁾	Min. Typ. Max. Units Conditions				Conditions
OC10	TccF	OC1 Output Fall Time	—	_		ns	See Parameter DO32
OC11	TccR	OC1 Output Rise Time	— — — ns See Parameter DO31				

Note 1: These parameters are characterized but not tested in manufacturing.

AC CHARACTERISTICS			$\begin{tabular}{ l l l l l l l l l l l l l l l l l l l$				
Maximum Data Rate	Master Transmit Only (Half-Duplex)	Master Transmit/Receive (Full-Duplex)	Slave Transmit/Receive (Full-Duplex)	CKE	СКР	SMP	
15 MHz	Table 25-30		_	0,1	0,1	0,1	
9 MHz		Table 25-31	—	1	0,1	1	
9 MHz	_	Table 25-32	—	0	0,1	1	
15 MHz	_	—	Table 25-33	1	0	0	
11 MHz		_	Table 25-34	1	1	0	
15 MHz	_	—	Table 25-35	0	1	0	
11 MHz	_	—	Table 25-36	0	0	0	

TABLE 25-29: SPIx MAXIMUM DATA/CLOCK RATE SUMMARY









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